



LTV-352T

Spec No.: DS70-2001-002 Effective Date: 10/27/2016

Revision: K

**LITE-ON DCC** 

**RELEASE** 

BNS-OD-FC001/A4



#### 1. DESCRIPTION

#### 1.1 Features

- Current transfer ratio ( CTR : MIN. 1000% at  $I_F = 1$ mA,  $V_{CE} = 2$ V )
- High input-output isolation voltage (Viso = 3,750Vrms)
- High collector-emitter voltage ( V<sub>CEO</sub> = 300V )
- Mini-flat package: 2.0mm profile: LTV-352T
- SOP-4 package
- Safety approval

UL 1577 & cUL

VDE DIN EN60747-5-5 (VDE 0884-5),

CSA CA5A

FIMKO/DEMKO/SEMKO/NEMKO

- RoHS Compliance
  - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- ESD pass HBM 8000V/ MM2000V/ CDM2000V
- MSL class1

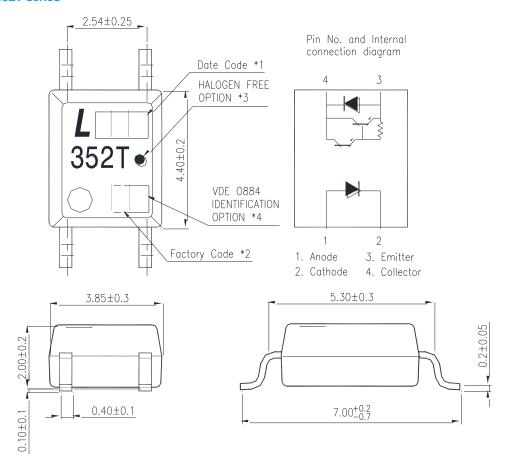
#### 1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers



#### 2. PACKAGE DIMENSIONS

#### 2.1 LTV-352T series



#### Notes:

- 1. 1-digit year code, Example : 2010 = A 2-digit work week ranging from '01' to '53'
- 2. Factory identification mark shall be marked (W: China -CZ, X: China -TJ)
- "●" indicates halogen free option.
- 4. "4"or"V" for VDE option.

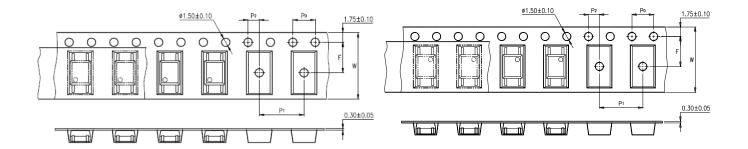
<sup>\*</sup>All dimensions in millimeters.



#### 3. TAPING DIMENSIONS

#### 3.1 LTV-352T-TP

#### 3.2 LTV-352T-TP1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	12±0.3 (0.472)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.157)
Distance of compartment	F	5.5±0.1 (0.217)
	P <sub>2</sub>	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	8±0.1 (0.315)

#### 3.3 Quantities Per Reel

Package Type	LTV-352T series
Quantities (pcs)	3000



#### 4. RATING AND CHARACTERISTICS

#### 4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
Input	Forward Current	l <sub>F</sub>	50	mA
	Reverse Voltage	$V_{R}$	6	V
	Power Dissipation	Р	70	mW
	Junction Temperature	ΤJ	125	°C
Output Collect	Collector - Emitter Voltage	$V_{\text{CEO}}$	300	V
	Emitter - Collector Voltage	V <sub>ECO</sub>	0.1	V
	Collector Current	Ic	150	mA
	Collector Power Dissipation	P <sub>C</sub>	150	mW
	Junction Temperature	Τ <sub>J</sub>	125	°C
	Total Power Dissipation	P <sub>tot</sub>	170	mW
1.	Isolation Voltage	$V_{\rm iso}$	3750	$V_{rms}$
	Operating Temperature	T <sub>opr</sub>	-55 ~ +110	°C
	Storage Temperature	T <sub>stg</sub>	-55 ~ +150	°C
2.	Soldering Temperature	T <sub>sol</sub>	260	°C

#### 1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



#### 4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Input	Forward Voltage	$V_{F}$	_	1.2	1.4	V	I <sub>F</sub> =10mA
	Reverse Current	I <sub>R</sub>	_	_	10	μА	V <sub>R</sub> =4V
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
Output	Collector Dark Current	I <sub>CEO</sub>	_	_	200	nA	V <sub>CE</sub> =200V, I <sub>F</sub> =0
	Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	300	_	_	V	I <sub>C</sub> =0.1mA, I <sub>F</sub> =0
	Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	0.1	_	_	V	I <sub>E</sub> =10μΑ, I <sub>F</sub> =0
TRANSFER CHARACTERISTICS	Collector Current	Ic	10	_	_	mA	I <sub>F</sub> =1mA
	Current Transfer Ratio	CTR	1000	5000	_	%	V <sub>CE</sub> =2V
	Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	_	1.2	V	$I_F=20$ mA $I_C=100$ mA
	Isolation Resistance	R <sub>iso</sub>	5×10 <sup>10</sup>	1×10 <sup>11</sup>	_	Ω	DC500V, 40 ~ 60% R.H.
	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Cut-Off Frequency	fc	1	7	_	kHz	$V_{CE}$ =2V, $I_{C}$ =20mA $R_{L}$ =100 $\Omega$ , -3dB
	Response Time (Rise)	tr	_	100	300	μS	V <sub>CE</sub> =2V,
	Response Time (Fall)	tf	_	20	100	μS	$I_C$ =20mA $R_L$ =100 $\Omega$

1. CTR = 
$$\frac{I_C}{I_F} \times 100\%$$



### 5. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

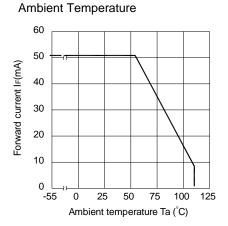


Fig.3 Collector-emitter saturation Voltage vs. Forward current

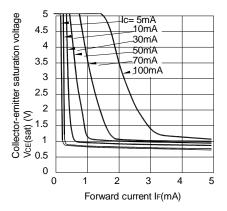


Fig.5 Current Transfer Ratio vs. Forward Current

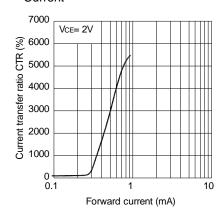


Fig.2 Collector Power Dissipation vs.
Ambient Temperature

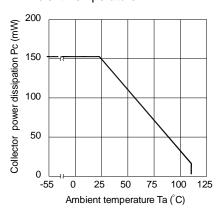


Fig.4 Forward Current vs. Forward Voltage

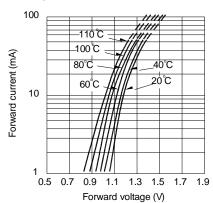


Fig.6 Collector Current vs.
Collector-emitter Voltage

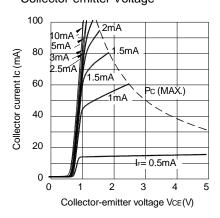




Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

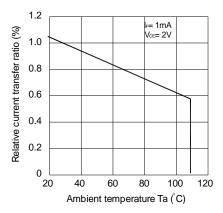


Fig.9 Collector Dark Current vs.

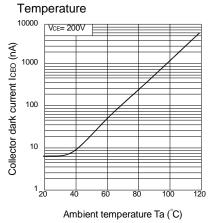


Fig.11 Frequency Response

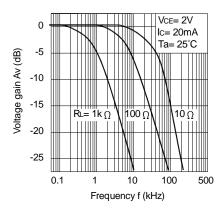


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

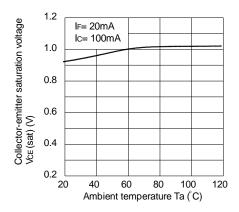
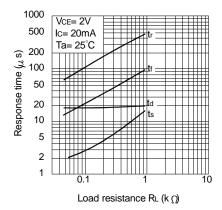
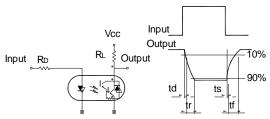


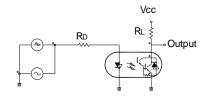
Fig.10 Response Time vs. Load Resistance



Test Circuit for Response Time



Test Circuit for Frequency Response



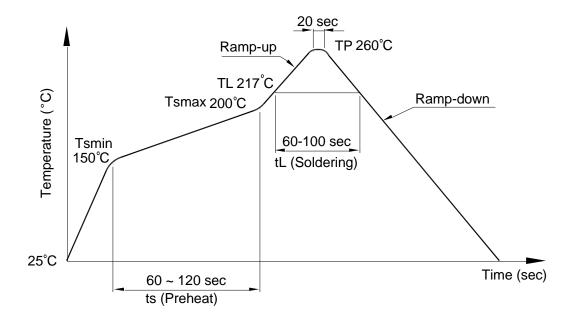


#### 6. TEMPERATURE PROFILE OF SOLDERING

#### 6.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions
Preheat	
- Temperature Min (T <sub>Smin</sub> )	150°C
- Temperature Max (T <sub>Smax</sub> )	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (T <sub>L</sub> )	217°C
- Time (t <sub>L</sub> )	60 ~ 100 sec
Peak Temperature (T <sub>P</sub> )	260°C
Ramp-up rate	3°C / sec max.
Ramp-down rate	3~6°C / sec





#### 6.2 Wave soldering (JEDEC22A111 compliant)

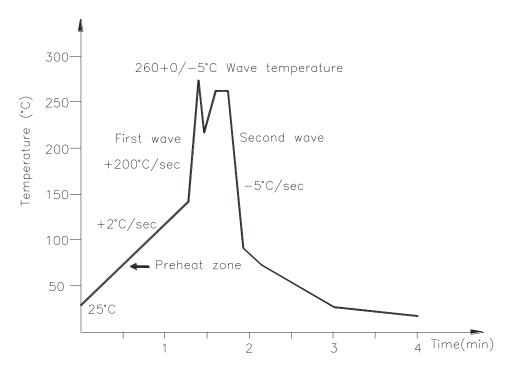
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



#### 6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

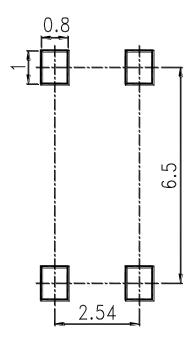
Temperature: 380+0/-5°C

Time: 3 sec max.



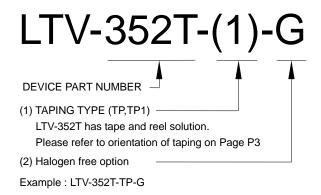
### 7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm





#### 8. NAMING RULE



LTV 352T(1)-V-0	j
DEVICE PART NUMBER —	
(1) TAPING TYPE (TP,TP1)  LTV-352T has tape and reel solution.  Please refer to orientation of taping on Page P3	
(2) VDE option	
(3) Halogen free option	
Example: LTV352TTP-V-G	

#### 9. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.